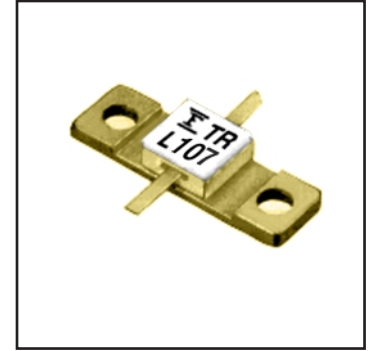


### FEATURES

- High Output Power:  $P_{1dB}=29.5\text{dBm}$  (Typ.)
- High Gain:  $G_{1dB}=13.5\text{dB}$  (Typ.)
- High PAE:  $\eta_{add}=47\%$  (Typ.)
- Proven Reliability
- Hermetically Sealed Package



### DESCRIPTION

The FLL107ME is a Power GaAs FET that is specifically designed to provide high power at L-Band frequencies with gain, linearity and efficiency superior to that of silicon devices. The performance in multitone environments for Class AB operation make them ideally suited for base station applications. This device is assembled in hermetic metal/ceramic package.

Fujitsu's stringent Quality Assurance Program assures the highest reliability and consistent performance.

### ABSOLUTE MAXIMUM RATING (Ambient Temperature $T_a=25^\circ\text{C}$ )

Item	Symbol	Condition	Rating	Unit
Drain-Source Voltage	$V_{DS}$		15	V
Gate-Source Voltage	$V_{GS}$		-5	V
Total Power Dissipation	$P_t$	$T_c = 25^\circ\text{C}$	4.16	W
Storage Temperature	$T_{stg}$		-65 to +175	$^\circ\text{C}$
Channel Temperature	$T_{ch}$		175	$^\circ\text{C}$

Fujitsu recommends the following conditions for the reliable operation of GaAs FETs:

1. The drain-source operating voltage ( $V_{DS}$ ) should not exceed 10 volts.
2. The forward and reverse gate currents should not exceed 4.8 and -0.5 mA respectively with gate resistance of 400 $\Omega$ .
3. The operating channel temperature ( $T_{ch}$ ) should not exceed 145 $^\circ\text{C}$ .

### ELECTRICAL CHARACTERISTICS (Ambient Temperature $T_a=25^\circ\text{C}$ )

Item	Symbol	Test Conditions	Limit			Unit
			Min.	Typ.	Max.	
Saturated Drain Current	$I_{DSS}$	$V_{DS} = 5\text{V}, V_{GS} = 0\text{V}$	-	300	450	mA
Transconductance	$g_m$	$V_{DS} = 5\text{V}, I_{DS} = 200\text{mA}$	-	150	-	mS
Pinch-off Voltage	$V_p$	$V_{DS} = 5\text{V}, I_{DS} = 15\text{mA}$	-1.0	-2.0	-3.5	V
Gate Source Breakdown Voltage	$V_{GSO}$	$I_{GS} = -15\mu\text{A}$	-5	-	-	V
Output Power at 1dB G.C.P.	$P_{1dB}$	$V_{DS} = 10\text{V}$ $I_{DS} \approx 0.6I_{DSS}$ (Typ.), $f = 2.3\text{GHz}$	28.5	29.5	-	dBm
Power Gain at 1dB G.C.P.	$G_{1dB}$		12.5	13.5	-	dB
Power-added Efficiency	$\eta_{add}$		-	47	-	%
Thermal Resistance	$R_{th}$	Channel to Case	-	25	36	$^\circ\text{C}/\text{W}$

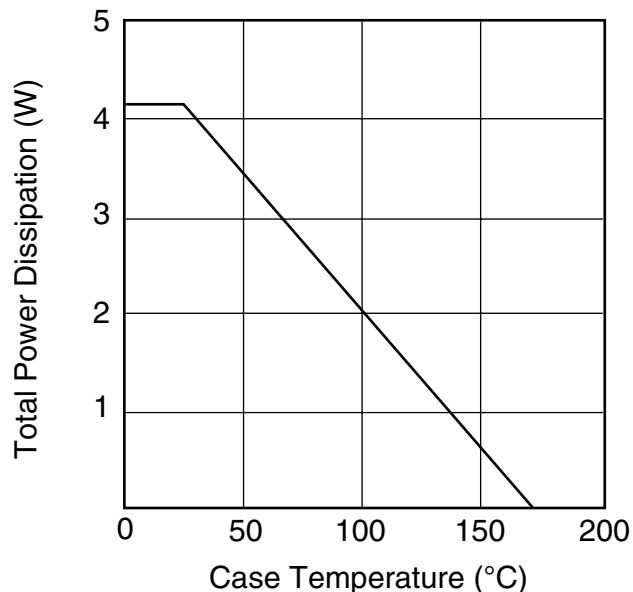
CASE STYLE: ME

G.C.P.: Gain Compression Point

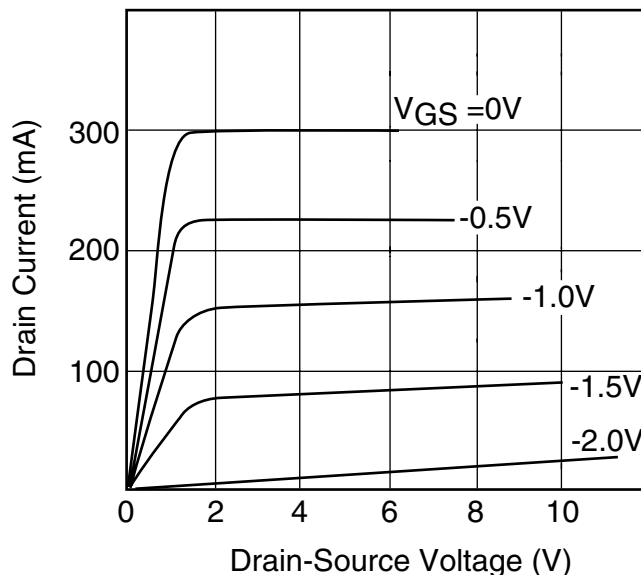
# FLL107ME

## L-Band Medium & High Power GaAs FET

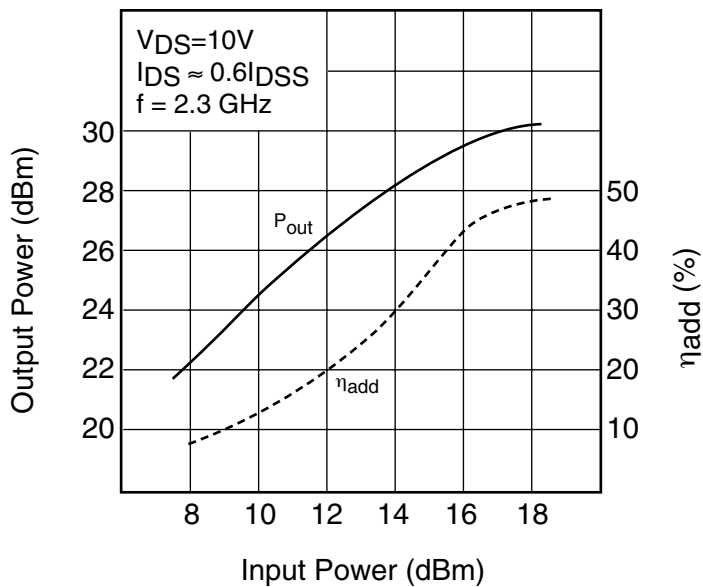
### POWER DERATING CURVE

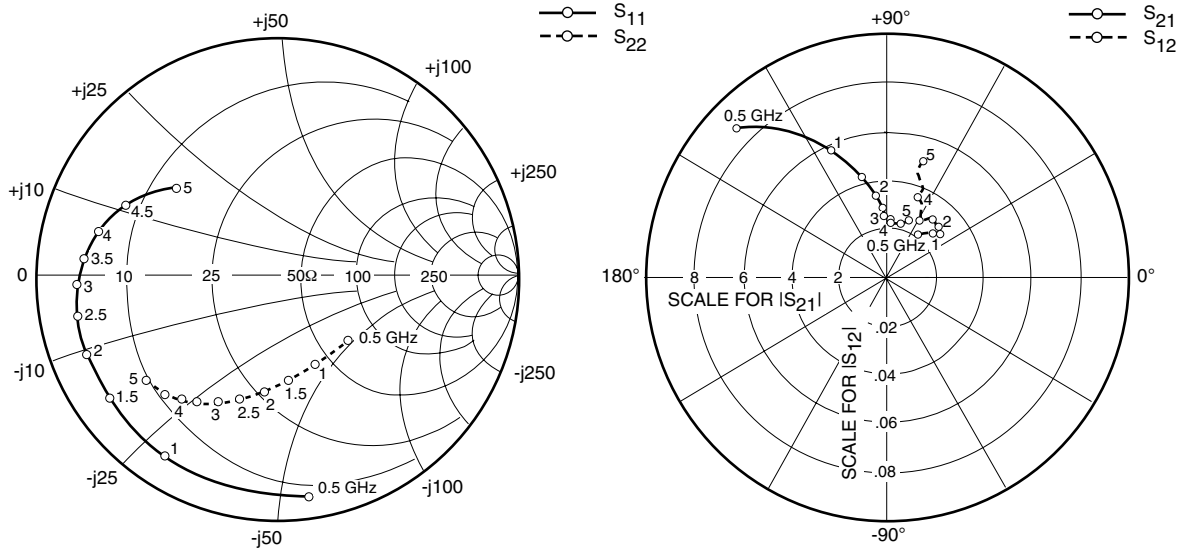


### DRAIN CURRENT vs. DRAIN-SOURCE VOLTAGE



### OUTPUT POWER vs. INPUT POWER





### S-PARAMETERS

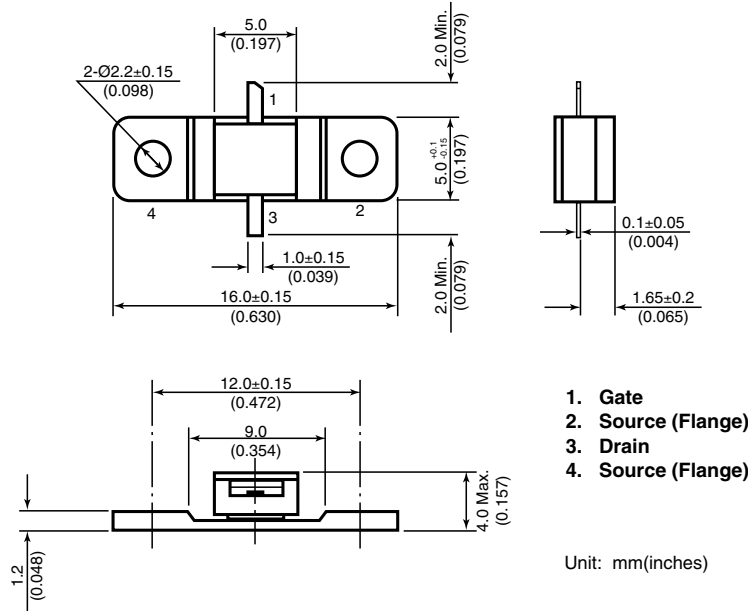
$V_{DS} = 10V, I_{DS} = 180mA$

FREQUENCY (MHZ)	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
500	.935	-81.9	8.704	135.4	.021	54.0	.404	-43.3
1000	.884	-121.5	5.761	114.2	.028	41.9	.408	-67.9
1500	.866	-143.2	4.260	104.9	.029	40.4	.443	-84.0
2000	.854	-157.4	3.368	98.0	.029	44.2	.494	-96.8
2500	.842	-167.6	2.823	94.2	.031	50.9	.545	-106.5
3000	.829	-176.8	2.526	92.3	.027	59.2	.585	-114.5
3500	.803	175.1	2.207	87.4	.033	64.1	.622	-121.9
4000	.761	166.3	2.350	87.7	.035	68.4	.651	-127.3
4500	.687	155.0	2.233	77.2	.039	67.5	.688	-132.7
5000	.554	138.8	2.436	70.3	.050	72.2	.699	-140.7

# FLL107ME

## L-Band Medium & High Power GaAs FET

### Case Style "ME" Metal-Ceramic Hermetic Package



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### CAUTION

Fujitsu Compound Semiconductor Products contain **gallium arsenide (GaAs)** which can be hazardous to the human body and the environment. For safety, observe the following procedures:

- Do not put these products into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

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